

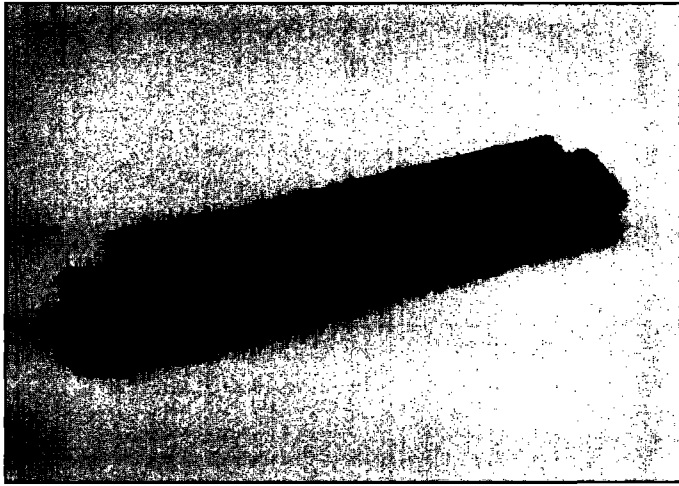
HIGH DENSITY CONNECTORS



PCB/Backplane Sockets, Vertical Mount

Single Bay

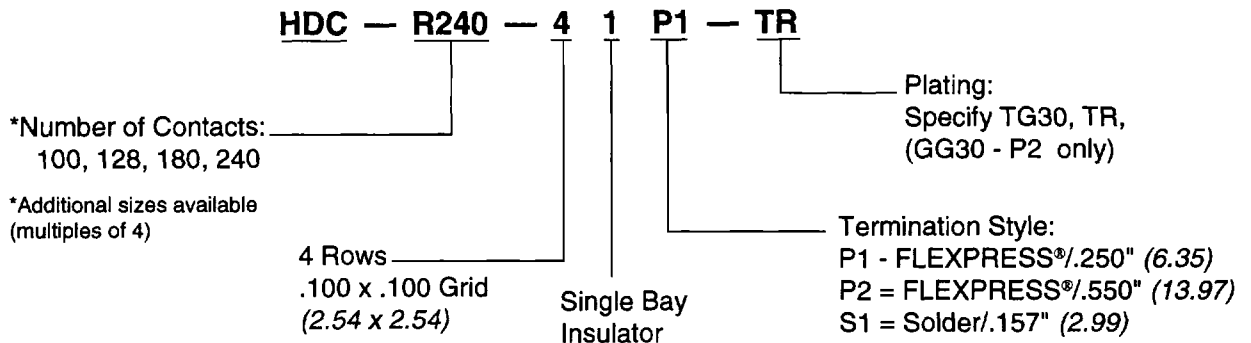
HDC - R4 Series



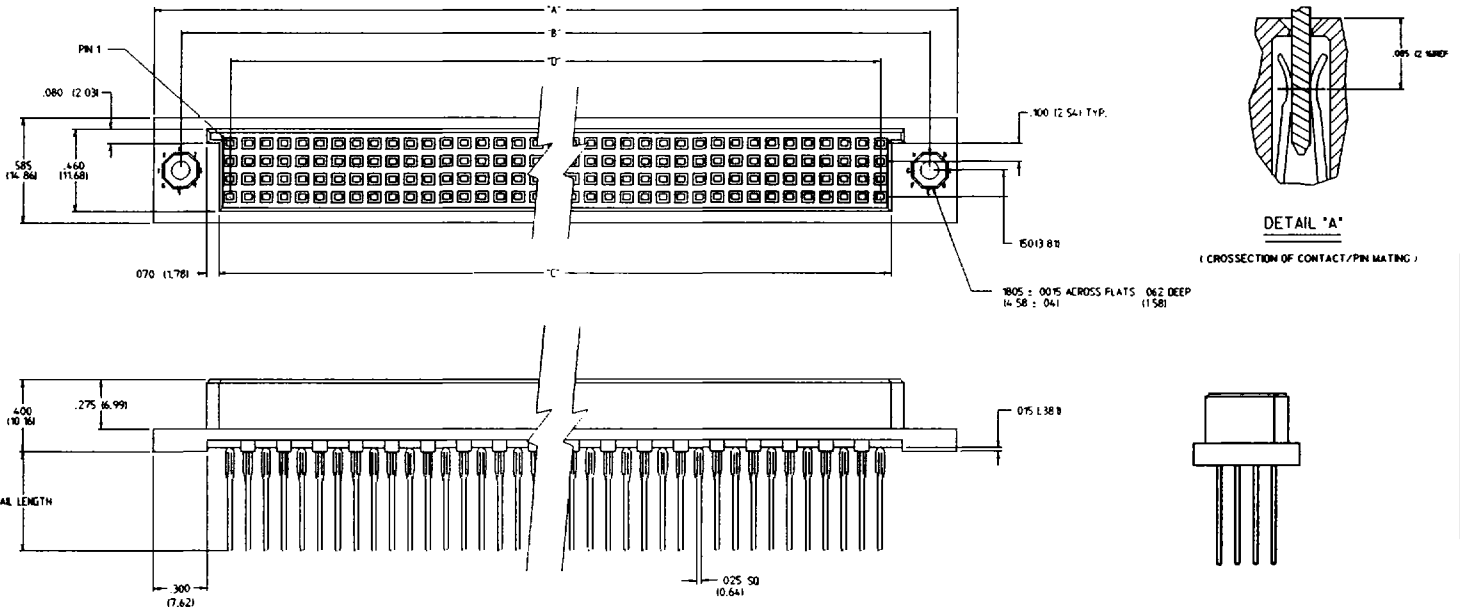
- Ideal for parallel PCB stacking
- High density interconnect for a variety of computer, telecom and high speed electronic equipment
- Press-fit FLEXPRESS® or solder type contacts
- Requires only flat push tool for installation
- Mates with 4 row single bay headers and plugs

DIN/HDC
BACKPLANE

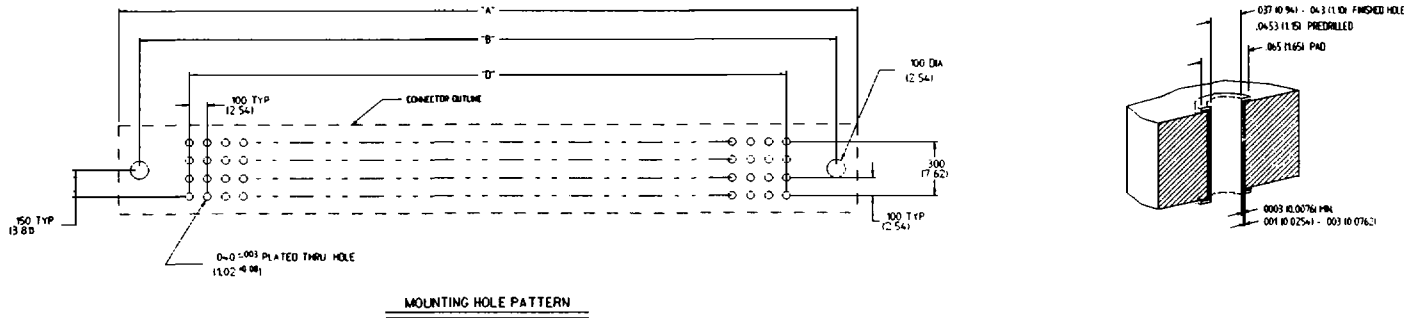
How to Order HDC-R Series Sockets



DESCRIPTION	"A" DIM	"B" DIM	"C" DIM	"D" DIM
HDC-R100-41XX-XX	3.250 (82.55)	2.950 (74.93)	2.524 (64.11)	2.400 (60.96)
HDC-R128-41XX-XX	3.950 (100.33)	3.650 (92.71)	3.224 (81.89)	3.100 (78.74)
HDC-R180-41XX-XX	5.250 (133.35)	4.950 (125.73)	4.524 (114.91)	4.400 (111.76)
HDC-R240-41XX-XX	6.750 (171.45)	6.450 (163.83)	6.024 (153.01)	5.900 (149.86)



DIN/HDC
BACKPLANE



Plating Description:

- TG30** = 30 μinch (.762 μm) minimum Gold on Area 1.
100 μinch (2.54 μm) minimum Tin /Lead on Area 4.
- TR** = 10 μinch (.254 μm) minimum ROBEX® on Area 1.
100 μinch (2.54 μm) minimum Tin /Lead on Area 4.
- GG30** = 30 μinch (.762 μm) minimum Gold on Area 1.
10 μinch (.254 μm) minimum gold on Area 2.
100 μinch (2.54 μm) minimum Tin /Lead on Area 3.

All options include:
50 μinch (1.27 μm) minimum Nickel underplate.

